

Electronic Patent Application Fee Transmittal

Application Number:	10680509			
Filing Date:	07-Oct-2003			
Title of Invention:	ADHESIVE BONDING WITH LOW TEMPERATURE GROWN AMORPHOUS OR POLYCRYSTALLINE COMPOUND SEMICONDUCTORS			
First Named Inventor/Applicant Name:	Kuang Chien Hsieh			
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Attorney Docket Number:	10322/57			
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Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	2501	1	720	720
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Total in USD (\$)				720